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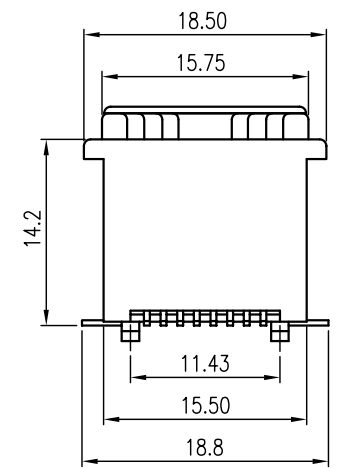
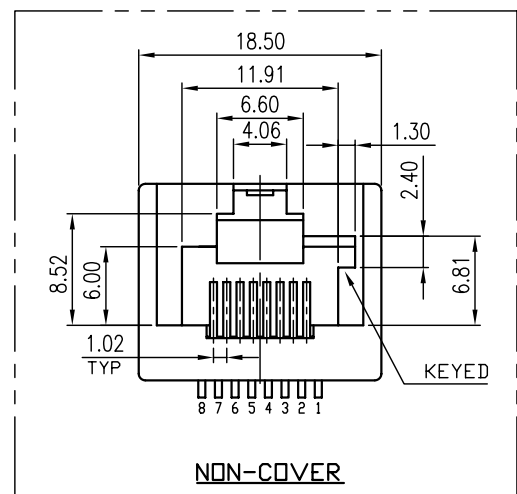
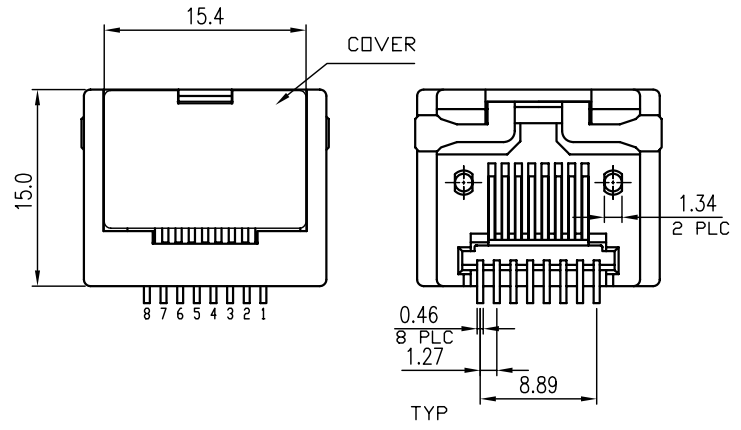
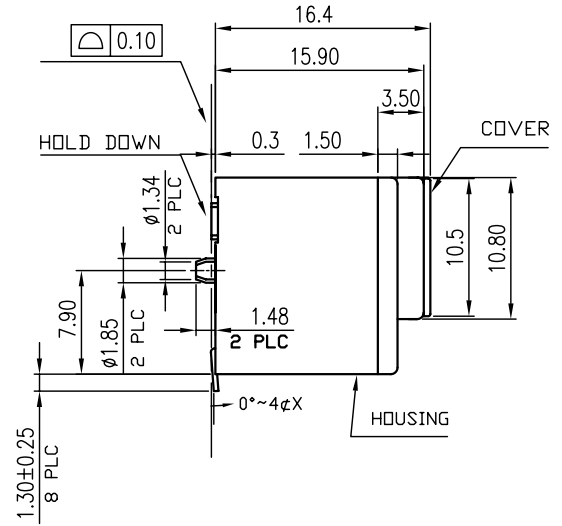
The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2002/95/EC for RoHS compliant.



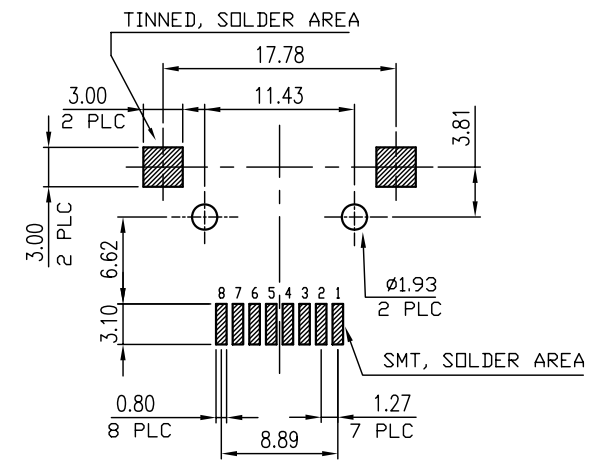
ORIGINAL



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		UNAPPROVED REVISION	04/13/2009	Arron Lin



- NOTES:**
- MATERIAL:**  
HOUSING: HIGH TEMPERATURE THERMO PLASTIC UL94V-0  
COVER: HIGH TEMPERATURE THERMO PLASTIC UL94V-0  
CONTACTS: PHOSPHOR BRONZE  
HOLD DOWN: COPPER ALLOY
  - FINISH:**  
CONTACTS:  
CONTACT AREA: GOLD PLATED. 30 μ" THICKNESS MIN.  
SOLDERING AREA: GOLD FLASH PLATED.  
UNDER PL.: NICKEL PLATED. 50 μ" THICKNESS MIN.  
HOLD DOWN:  
MATTE TIN PLATED. 50μ"~100 μ" THICKNESS.
  - THIS PRODUCT DOESN'T CONTAIN ENVIRONMENTAL HAZARDOUS MATERIAL PER DIRECTIVE 2002/95/EC FOR RoHS.
  - PACKING: PLEASE REFER TO PKS-G71B001



RECOMMENDED PCB LAYOUT (TOP VIEW)  
PCB THICKNESS=1.2MM  
GENERALLY TOLERONCE=±0.05

G71B 0238 4 00 EU	50μ"	TOLERANCE	APPROVALS	DATE	<b>TITLE</b> MODULAR JACK, 8P8C TOP ENTRY, SMT, W/ KEYED W/ HOLD DOWN & COVER	<b>Amphenol</b> <sup>®</sup> Amphenol Corporation Amphenol Taiwan Corporation	
G71B 0238 3 00 EU	30μ"	X. ±0.30	DRAWN Daniel Hsieh	04/13/2009			
G71B 0238 2 00 EU	15μ"	X.XX ±0.20	CHECKED Roger Tsai	04/13/2009			
G71B 0238 1 00 EU	6μ"	X.XXX ±0.10	APPROVED Hank Hsu	04/13/2009			
<b>PART NUMBER</b>	<b>FINISH</b>	<b>UNLESS OTHERWISE SPECIFIED</b>	<b>DWG TYPE</b>	<b>PROJECT CODE</b>		<b>UNIT</b> mm <b>SCALE</b> NA <b>SIZE</b> A3 <b>SHEET</b> 1 OF 2	<b>PART No.</b> G71B 0238X 00 EU <b>DWG No.</b> G71B0238X00EU <b>REV.</b> A

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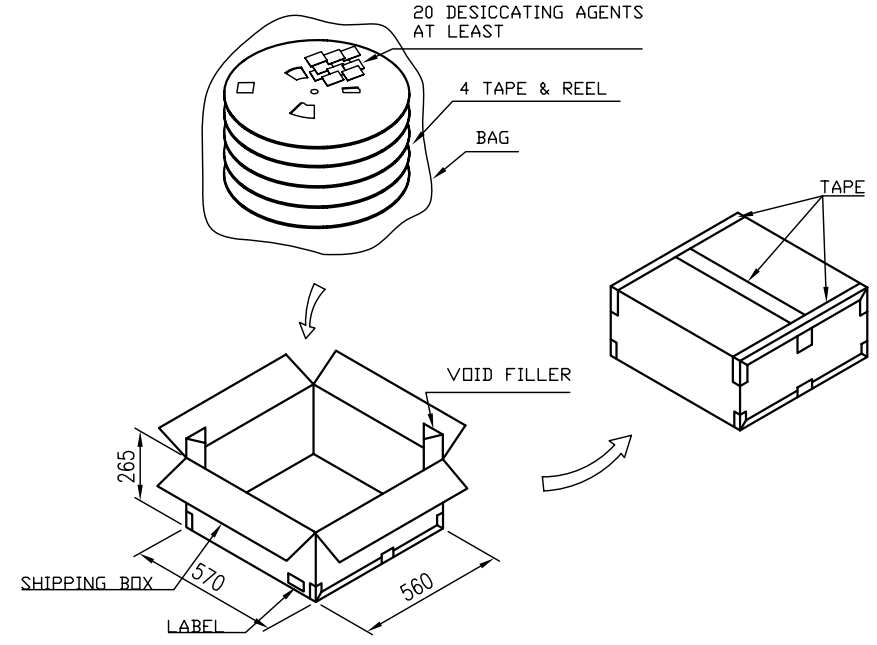
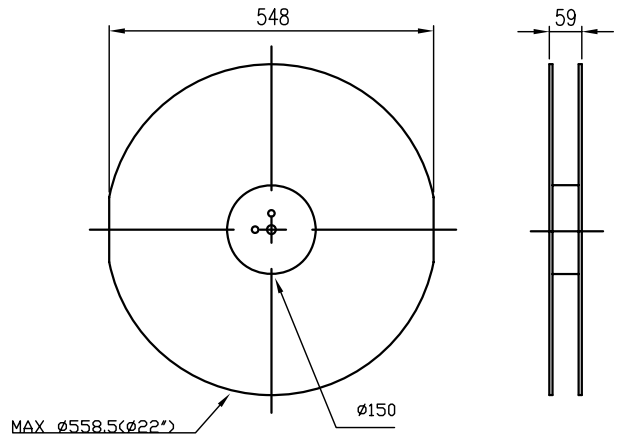
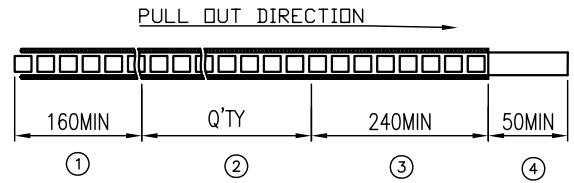
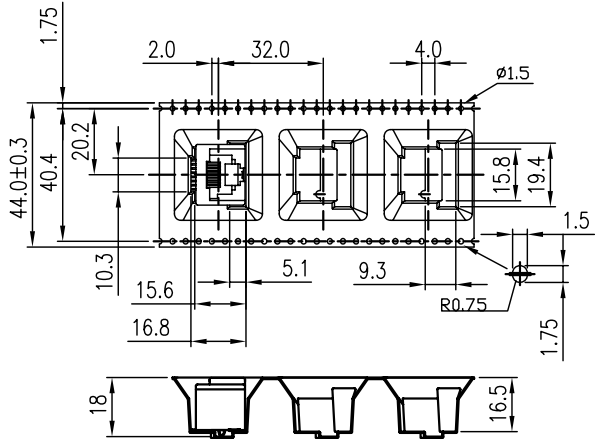
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ORIGINAL



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		UNAPPROVED REVISION	04/13/2009	Arron Lin



350	4	1400	8	5.5	G71B0238X00EU
PCS/REEL	REELS/BOX	QUANTITY (PCS)	G/W (Kg)	N/W (Kg)	PART NUMBER

TOLERANCE	APPROVALS	DATE	TITLE	UNIT	SIZE	PART No.
X. ±0.30	DRAWN Daniel Hsieh	04/13/2009	MODULAR JACK, 8P8C TOP ENTRY, SMT W/ HOLD DOWN & COVER	mm	A3	PKS-G71B001
X.X ±0.20	CHECKED Roger Tsai	04/13/2009				
X.XXX ±0.10	APPROVED Hank Hsu	04/13/2009				
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE MJK		SCALE NA	SHEET 2 OF 2	DWG No. PKS-G71B001
UNLESS OTHERWISE SPECIFIED						REV. A